

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	Toshikazu Okubo, <i>et al.</i>	Examiner:	Khiem D. Nguyen
Serial No.	10/550,153	Art Unit:	2823
Filed:	September 20, 2005	Confirmation No:	1053
Title:	Method for Analyzing Electrolytic Copper Plating Solution, and Analyzing Device Therefor and Production Method for Semi-Conductor Product		

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO RESTRICTION REQUIREMENT

This is a response to the Restriction Requirement dated April 8, 2008.

The Examiner has identified two separate and distinct inventions within the claims of the above-identified patent application, namely:

Group I Claims 1-4, 6-10, 12-16, 18-19, and 21, drawn to a method for analyzing a copper electroplating solution containing an additive; and

Group II Claims 5, 11, 17, and 20, drawn to an apparatus for analyzing a copper electroplating solution.

Applicants' election

Applicants elect Group II of Claims 5, 11, 17, and 20, drawn to an apparatus for analyzing a copper electroplating solution. The election is made without traverse. Applicants reserve their rights to filing a divisional application for Group I.